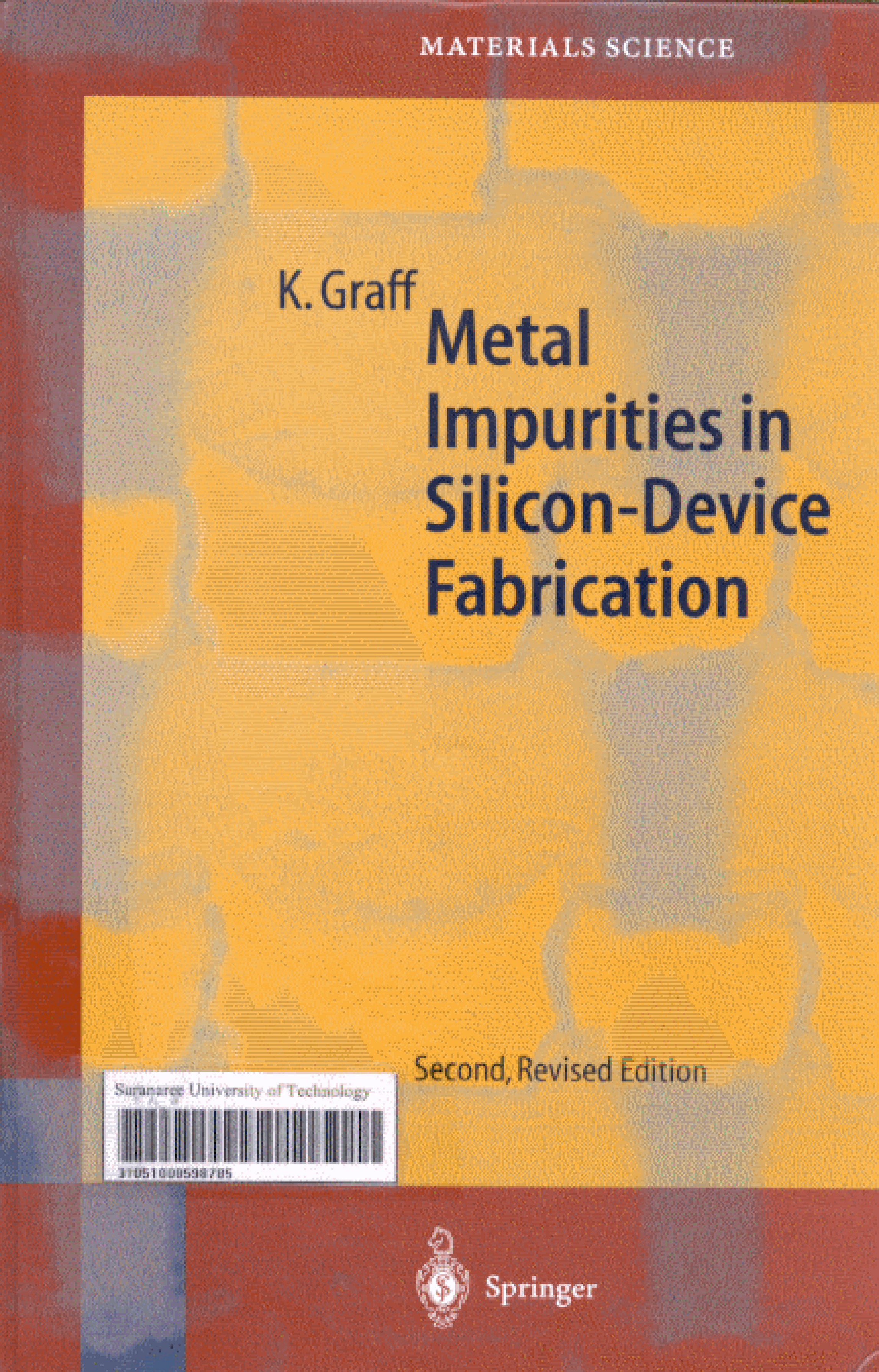

MATERIALS SCIENCE

K. Graff

Metal Impurities in Silicon-Device Fabrication

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Contents

1. **Introduction** 1

2. **Common Properties of Transition Metals** 5
   2.1 General Behavior 5
   2.2 Contamination of Silicon Wafers 9
      2.2.1 Solid Phase 9
      2.2.2 Liquid Phase 10
      2.2.3 Vapor Phase 12
   2.3 Impact on Device Performance 14
      2.3.1 Dissolved Transition Metals 15
      2.3.2 Precipitated Transition Metals 18

3. **Properties of Transition Metals in Silicon** 20
   3.1 Solubilities 21
   3.2 Diffusivities 25
   3.3 Dissolved Impurities 30
      3.3.1 Point Defects 32
      3.3.2 Complexes 42
   3.4 Precipitated Metals 51
      3.4.1 Volume Precipitates 52
      3.4.2 Surface Precipitates - Haze 58
      3.4.3 Haze Phenomena 63

4. **Properties of the Main Impurities** 76
   4.1 Iron 77
      4.1.1 Solubility 77
      4.1.2 Diffusivity 78
      4.1.3 Behavior During Heat Treatment 79
      4.1.4 Electrical Activity 80
      4.1.5 Properties of the Precipitates 86
      4.1.6 Known Impurity Sources, and Common Concentrations . 87
      4.1.7 Avoidance of Contamination 88
   4.2 Nickel 89
      4.2.1 Solubility 90
      4.2.2 Diffusivity 91
      4.2.3 Behavior During Heat Treatment 92
      4.2.4 Electrical Activity 93
      4.2.5 Properties of the Precipitates 95

    4.2.6 Known Impurity Sources, and Common Concentrations 96
    4.2.7 Avoidance of Contamination 97
4.3 Copper 98
    4.3.1 Solubility 99
    4.3.2 Diffusivity 99
    4.3.3 Behavior During Heat Treatment 100
    4.3.4 Electrical Activity 101
    4.3.5 Properties of the Precipitates 103
    4.3.6 Known Impurity Sources and Common Concentrations 104
    4.3.7 Avoidance of Contamination 105
4.4 Molybdenum 106
    4.4.1 Solubility 107
    4.4.2 Diffusivity 107
    4.4.3 Behavior During Heat Treatment 108
    4.4.4 Electrical Activity 108
    4.4.5 Properties of the Precipitates 108
    4.4.6 Known Impurity Sources and Common Concentrations 108
    4.4.7 Avoidance of Contamination 109
4.5 Palladium 109
    4.5.1 Solubility 110
    4.5.2 Diffusivity 111
    4.5.3 Behavior During Heat Treatment 112
    4.5.4 Electrical Activity 113
    4.5.5 Properties of the Precipitates 115
    4.5.6 Known Impurity Sources and Common Concentrations 117
4.6 Platinum 117
    4.6.1 Solubility 118
    4.6.2 Diffusivity 119
    4.6.3 Behavior During Heat Treatment 120
    4.6.4 Electrical Activity 121
    4.6.5 Properties of the Precipitates 123
    4.6.6 Known Impurity Sources and Common Concentrations 123
    4.6.7 Avoidance of Contamination 123
4.7 Gold 124
    4.7.1 Solubility 125
    4.7.2 Diffusivity 125
    4.7.3 Behavior During Heat Treatment 126
    4.7.4 Electrical Activity 127
    4.7.5 Properties of the Precipitates 129
    4.7.6 Known Impurity Sources and Common Concentrations 129
    4.7.7 Avoidance of Contamination 130

5. **Properties of Rare Impurities** 131

3d Transition Metals

5.1 Scandium 132
5.2 Titanium 134
5.3 Vanadium 136
5.4 Chromium 138
5.5 Manganese 141
5.6 Cobalt 144
5.7 Zinc 147

4d Transition Metals

5.8 Zircon 149
5.9 Niobium 150
5.10 Ruthenium 151
5.11 Rhodium 151
5.12 Silver 153
5.13 Cadmium 156

5d Transition Metals

5.14 Hafnium 157
5.15 Tantalum 157
5.16 Tungsten 158
5.17 Rhenium 160
5.18 Osmium 160
5.19 Iridium 161
5.20 Mercury 162

6. **Detection Methods** 163
6.1 Detection of Total Impurity Content 163
6.1.1 Neutron Activation Analysis 164
6.1.2 Mass Spectrometers, Secondary Ion Mass Spectrometers 164
6.1.3 Atomic Absorption Spectroscopy 165
6.1.4 Vapor-Phase Decomposition 165
6.1.5 Inductively-Coupled Plasma Spectroscopy 166
6.1.6 Total-Reflection X-Ray Fluorescence Analysis 166
6.2 Detection of Dissolved Impurities 168
6.2.1 Deep Level Transient Spectroscopy 169
6.2.2 Carrier Lifetime 177
6.2.3 Diffusion Length 181
6.3 Detection of Precipitates 185
6.3.1 Haze Test 186

7. **Requirements of Modern Technology** 190
7.1 Reduction of Contamination 192
7.1.1 Control of Ingots 192
7.1.2 Process Control 198

8. Gettering of Impurities 201
8.1 Gettering Mechanisms 202
8.2 Control of Gettering Efficiency 207
8.2.1 Conventional Methods 207
8.2.2 Palladium Test 208
8.2.3 Iron Test 215

9. Conclusion and Future Trends 233

Appendix 239

References 246

Subject Index 267